






























Impedance & Stackup Report

Single Ended								
Index	Layer	Imp Model	WithCoat	Ref Layer	Orginal LW/LS(mil)	Adjusted LW/LS(mil)	Adjusted Imp(ohm)	Org Imp (ohm)
1	L1		Y	L2	ORG_LW: 5.800	ADJ_LW: 5.500	49.98	50.0+/-10%
2	L3		N	L4/L2	ORG_LW: 3.600	ADJ_LW: 3.600	49.61	50.0+/-10%
3	L3		N	L4/L2	ORG_LW: 5.800	ADJ_LW: 5.800	39.83	40.0+/-12%
4	L8		N	L7/L9	ORG_LW: 5.800	ADJ_LW: 5.800	39.78	40.0+/-12%
5	L8		N	L7/L9	ORG_LW: 3.600	ADJ_LW: 3.600	49.57	50.0+/-10%
6	L10		Y	L9	ORG_LW: 5.800	ADJ_LW: 5.500	49.98	50.0+/-10%
Differential								
Index	Layer	Imp Model	WithCoat	Ref Layer	Orginal LW/LS(mil)	Adjusted LW/LS(mil)	Adjusted Imp(ohm)	Org Imp (ohm)
7	L1		Y	L2	ORG_LW: 4.250 ORG_S: 7.150	ADJ_LW: 4.250 ADJ_S: 7.150	99.29	100.0+/-10%
8	L1		Y	L2	ORG_LW: 4.200 ORG_S: 4.400	ADJ_LW: 4.200 ADJ_S: 4.400	90.08	90.0+/-10%
9	L3		N	L4/L2	ORG_LW: 3.700 ORG_S: 6.000	ADJ_LW: 3.600 ADJ_S: 6.100	90.37	90.0+/-10%
10	L3		N	L4/L2	ORG_LW: 4.200 ORG_S: 4.300	ADJ_LW: 4.200 ADJ_S: 4.300	79.52	80.0+/-10%
11	L8		N	L7/L9	ORG_LW: 4.200 ORG_S: 4.300	ADJ_LW: 4.200 ADJ_S: 4.300	79.48	80.0+/-10%
12	L8		N	L7/L9	ORG_LW: 3.700 ORG_S: 6.000	ADJ_LW: 3.600 ADJ_S: 6.100	90.32	90.0+/-10%
13	L10		Y	L9	ORG_LW: 4.200 ORG_S: 4.400	ADJ_LW: 4.200 ADJ_S: 4.400	90.08	90.0+/-10%
14	L10		Y	L9	ORG_LW: 4.250 ORG_S: 7.150	ADJ_LW: 4.250 ADJ_S: 7.150	99.29	100.0+/-10%
Index	Layer	Imp Model	WithCoat	Ref Layer	Orginal LW/LS(mil)	Adjusted LW/LS(mil)	Adjusted Imp(ohm)	Org Imp (ohm)
15	L1		Y	L3	ORG_LW:16.000 ORG_D:14.000	ADJ_LW:14.200 ADJ_D:14.900	50.11	50.0+/-10%

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叠板图:

Lyr	残铜率_铜质	Image	1G DK	芯板结构	客户要求(mil)	物料名称(mil)
gtl	CU(%):43 0.33OZ finish 1oz		0.000			三井 Foil 0.33oz
			3.980		3.7+0.71/-0.71mil	IT180ABS 2113 RC58
12s	CU(%):77 1OZ		4.290	2116*1		IT180A 3.94mil 1/1(不含铜)
13s	CU(%):57 1OZ		3.910			IT180ABS 1080 RC63
			4.050		6.61+1.5/-1.5mil	IT180ABS 2116 RC54
14s	CU(%):77 1OZ		4.350	1506*1		IT180A 5.91mil 1/1(不含铜)
15s	CU(%):72 1OZ		4.050			IT180ABS 2116 RC54
			4.050		9.02+1.5/-1.5mil	IT180ABS 2116 RC54
16s	CU(%):64 1OZ		4.350	1506*1		IT180A 5.91mil 1/1(不含铜)
17s	CU(%):77 1OZ		4.050			IT180ABS 2116 RC54
			3.910		6.61+1.5/-1.5mil	IT180ABS 1080 RC63
18s	CU(%):54 1OZ		4.290	2116*1		IT180A 3.94mil 1/1(不含铜)
19s	CU(%):77 1OZ		3.980		3.7+0.71/-0.71mil	IT180ABS 2113 RC58
gbl	CU(%):42 0.33OZ finish 1oz		0.000			三井 Foil 0.33oz

Finish Board Thickness(mil): 62.20+ 6.22/- 6.22